

MCP7Y10-Nxxx 800Gbs Twin-port OSFP to 2x400G QSFP112 DAC Splitter 1-3m Product Specifications

Table of contents

Transceiver Connectivity Scenarios	4
Pin Description	5
Specifications	10
Part Numbers and Description	20
Document Revision History	21

Introduction

NVIDIA® MCP7Y10 is an 800Gb/s Twin-port OSFP (Octal Small Form-factor Pluggable) -to-2x 400Gb/s QSFP112 (Quad Small Form-factor Pluggable 112G) passive Direct Attach Copper (DAC) dual breakout (aka splitter) cable for 400Gb/s NVIDIA End-to-End Infiniband and Ethernet solutions. It has identical design and internals as the Single port OSFP version, only with different connector shells. The DAC firmware supports both InfiniBand and Ethernet and is automatically enabled depending on the protocol of the switch attached to.

The 8-channel Twin port OSFP end uses a finned top form-factor for use in Quantum-2 and Spectrum-4 switch cages. The two 400G ends support 4-channels of 100G-PAM4 (400G) and use a flat top QSFP112 for use in ConnectX-7 adapters and BlueField-3 DPUs using riding heat sinks on the connector cage.

DAC cables are the lowest-cost, lowest-latency, near zero power consuming high-speed links available due to their simplicity of design and minimal components. The "passive" term refers to the copper cable containing no electronics in the data path. Each end includes an EEPROM which provides product identification and characteristics to the host system. Every cable length is tuned to reduce internal signal noise and back reflections. Thin 30AWG is used for 1 &1.5-meter lengths and thicker 26AWG for 2-3-meters.

Main use is linking an 800Gb/s Quantum-2 switch or Spectrum-4 switch to QSFP112-based 400Gb/s ConnectX-7 PCle network adapters cards and BlueField-3 DPUs.

NVIDIA's cable solutions provide power-efficient connectivity enabling higher port bandwidth, density and configurability at a low cost and reduced power requirement in the data centers. Rigorous cable production testing ensures best out-of-the-box installation experience, performance, and durability.



(i) Note

Images are for illustration purposes only. Product labels, colors, and lengths may vary.

Key Features

- 800Gb/s to two 400Gb/s data rates
- 100G-PAM4 modulation
- 1-3m lengths
- OSFP and QSFP112 ends each consume 0.1Watts
- Operating case temperature 0-70°C
- Hot pluggable
- RoHS compliant
- CMIS compliant
- LSZH (Low Smoke Zero Halogen) jacket

Applications

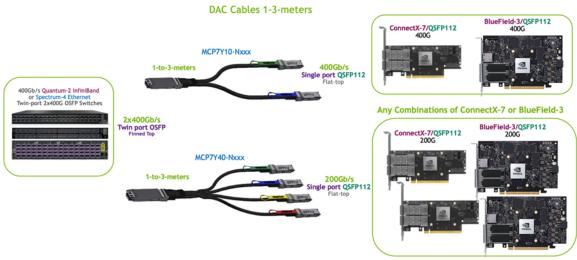
• 2x400G NDR InfiniBand Quantum-2 or Spectrum-4 Ethernet switch-to-two 400Gb/s QSFP112 ConnectX-7 and/or BlueField-3 DPUs

Transceiver Connectivity Scenarios

The single port QSFP112 use is with ConnectX-7/QSFP112 network adapters and BlueField-3/QSFP112 DPUs.

DAC: 400G IB/EN SWITCH-TO- 2X AND 4X CONNECTX-7/ QSFP112

Twin port OSFP 2x400G to 2x 400G and 4x 200G single port



The splitter DAC cables are available in:

- 1. MCP7Y10 1:2 splits (2x 400G) (4-channels x 100G-PAM4)
- 2. MCP7Y40: 1:4 splits (4x 200G) (2-channels x 100G-PAM4)

(i) Note

Active Copper Cables (ACC) are also available for lengths of 4 and 5-meters.

Pin Description

The MCP7Y10 DAC is OSFP (Octal Small Form Factor Pluggable). The pin assignment for the interface is shown below.

OSFP Pin Description

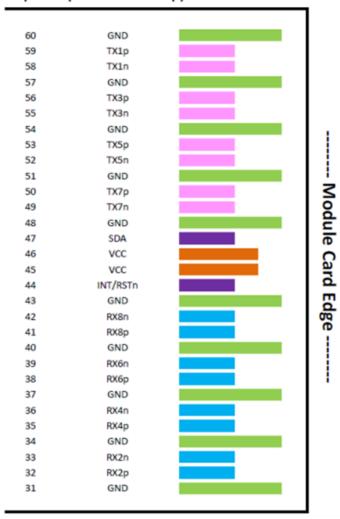
Pi n	Symbol	Description	Pi n	Symbol	Description
1	GND	Ground	31	GND	Ground
2	Tx2p	Transmitter Non-Inverted Data Input	32	Rx2p	Receiver Non-Inverted Data Output
3	Tx2n	Transmitter Inverted Data Input	33	Rx2n	Receiver Inverted Data Output
4	GND	Ground	34	GND	Grounds
5	Тх4р	Transmitter Non-Inverted Data Input	35 Rx4n		Receiver Non-Inverted Data Output
6	Tx4n	Transmitter Inverted Data Input	36	Rx4n	Receiver Inverted Data Output
7	GND	Ground	37	GND	Ground
8	Тх6р	Transmitter Non-Inverted Data Input	38	Rx6p	Receiver Non-Inverted Data Output
9	Tx6n	Transmitter Inverted Data Input	39	Rx6n	Receiver Inverted Data Output
10	GND	Ground	40	GND	Ground
11	Тх8р	Transmitter Non-Inverted Data input	41	Rx8p	Receiver Non-Inverted Data Output
12	Tx8n	Transmitter Inverted Data Input	42	Rx8n	Receiver Inverted Data Output
13	GND	Ground	43	GND	Ground
14	SCL	2-wire serial interface clock	44	INT / RSTn	Module Interrupt / Module Reset

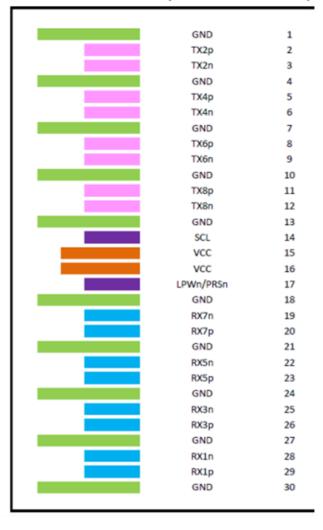
Pi n	Symbol	Description	Pi n	Symbol	Description
15	VCC	+3.3V Power	45	VCC	+3.3V Power
16	VCC	+3.3V Power	46	VCC	+3.3V Power
17	LPWn / PRSn	Low-Power Mode / Module Present	47	SDA	2-wire Serial interface data
18	GND	Ground	48	GND	Ground
19	Rx7n	Receiver Inverted Data Output	49	Tx7n	Transmitter Inverted Data Input
20	Rx7p	Receiver Non-Inverted Data Output	50	Тх7р	Transmitter Non-Inverted Data Input
21	GND	Ground	51	GND	Ground
22	Rx5n	Receiver Inverted Data Output	52	Tx5n	Transmitter Inverted Data Input
23	Rx5p	Receiver Non-Inverted Data Output	53	Тх5р	Transmitter Non-Inverted Data Input
24	GND	Ground	54	GND	Ground
25	Rx3n	Receiver Inverted Data Output	55	Tx3n	Transmitter Inverted Data Input
26	Rx3p	Receiver Non-Inverted Data Output	56	Тх3р	Transmitter Non-Inverted Data Input
27	GND	Ground	57	GND	Ground
28	Rxln	Receiver Inverted Data Output	58	Txln	Transmitter Inverted Data Input
29	Rxlp	Receiver Non-Inverted Data Output	59	Txlp	Transmitter Non-Inverted Data Input
30	GND	Ground	60	GND	Ground

OSFP Module Pad Layout (800Gb/s End)

Top Side (viewed from top)

Bottom Side (viewed from bottom)



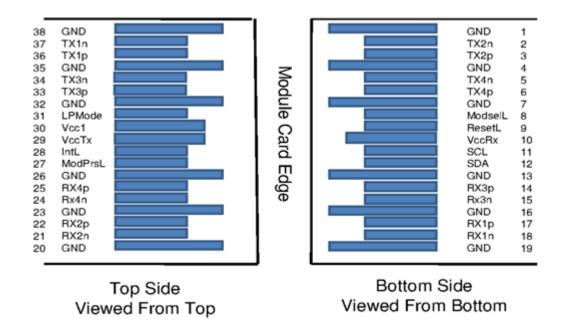


QSFP Pin Description (400Gb/s Ends)

Pi n	Symb ol	Description	Pi n	Symb ol	Description
1	Groun d	Ground	2	Groun d	Ground
2	Tx2n	Connected to Port 1 lane Rx2 Inverted Data	2	Rx2n	Connected to Port 1 lane Tx2 Inverted Data
3	Tx2p	Connected to Port 1 lane Rx2 Non-Inverted Data	2	Rx2p	Connected to Port 1 lane Tx2 Non-Inverted Data
4	Groun d	Ground	2	Groun d	Grounds

Pi n	Symb	Description	Pi n	Symb	Description
5	Tx4n	Connected to Port 2 lane Rx2 Non-Inverted Data	2 4	Rx4n	Connected to Port 2 lane Tx2 Inverted Data
6	Тх4р	Connected to Port 2 lane Rx2 Inverted Data	2 5	Rx4p	Connected to Port 2 lane Tx2 Non-Inverted Data
7	Groun d	Ground	2 6	Groun d	Ground
8	Mod- SelL	Cable Select	2 7	ModP rsL	Cable Present
9	Reset	Cable Reset	2 8	IntL	Interrupt
1	Vcc Rx	+3.3V Power supply receiver	2	Vcc Tx	+3.3V Power supply transmitter
1	SCL	2-wire serial interface clock	3	Vcc1	+3.3V Power Supply
1 2	SDA	2-wire serial interface data	3	LPMo de	Low Power Mode
1 3	Groun d	Ground	3 2	Groun d	Ground
1 4	Rx3p	Connected to Port 2 lane Tx1 Non-Inverted Data	3	ТхЗр	Connected to Port 2 lane Rx1 Non-Inverted Data
1 5	Rx3n	Connected to Port 2 lane Tx1 Inverted Data	3 4	Tx3n	Connected to Port 2 lane Rx1 Inverted Data
1	Groun d	Ground	3 5	Groun d	Ground
1 7	Rx1p	Connected to Port 1 lane Tx1 Non-Inverted Data	3 6	Тх1р	Connected to Port 1 lane Rx1 Non-Inverted Data
1	Rx1n	Connected to Port 1 lane Tx1 Inverted Data	3 7	Txln	Connected to Port 1 lane Rx1 Inverted Data
1	Groun d	Ground	3 8	Groun d	Ground

QSFP Module Pad Layout



Diagnostics and Other Features

The product complies with the CMIS 4.0 specifications for the management interfaces. These interfaces provide Digital Diagnostic Monitoring (DDM) functions including warning and alarms:

- Rx receive optical power monitor
- Tx transmit optical power monitor
- Tx bias current monitor
- Module supply voltage monitor
- Module case temperature monitor

The AOC provides the following features and interrupt indications

- Tx & Rx LOS
- Tx & Rx LoL
- Tx fault
- Tx & Rx disable

Specifications

Absolute Maximum Specifications

Absolute maximum ratings are those beyond which damage to the device may occur.

Prolonged operation between the operational specifications and absolute maximum ratings is not intended and may cause permanent device degradation.

Parameter	Min	Max	Units
Supply voltage	-0.3	3.6	V
Data input voltage	-0.3	3.6	V
Control input voltage	-0.3	3.6	V

Environmental Specifications

This table shows the environmental specifications for the product.

Parameter	Min	Max	Units
Storage temperature	-40	85	°C

Operational Specifications

This section shows the range of values for normal operation.

Parameter	Min	Тур	Max	Units
Supply voltage (V _{cc})	3.135	3.3	3.465	V
Power consumption			0.1	W
Operating case temperature	0		70	°C
Operating relative humidity	5		85	%

Electrical Specifications

Parameter	Min	Тур	Max	Units	Note
Characteristic impedance	90	100	110	Ω	
Time propagation delay			4.5	ns/m	Informative

Mechanical Specifications

Parameter	Value	Units	
Diameter	30AWG: 7.2 ±0.03 26AWG: 8.9 ±0.03		mm
Langth talarana	length < 2 m	±25	
Length tolerance	length >= 2 m	mm	

Minimum bend radius

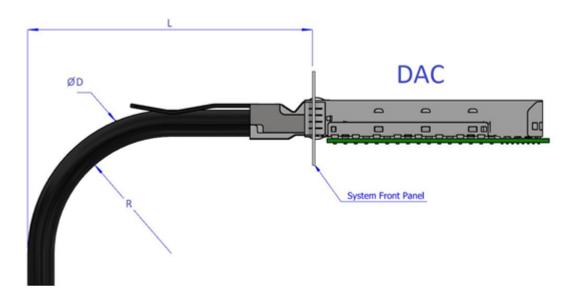
OPN	Length (m)	AWG (mm)	Cable Diameter (mm)	Min bend radius R (mm)	Assembly Space L** Combined/Single (mm)
MCP7Y10 -N001	1.0	30, 2x8pair s	7.2	72	135/128
MCP7Y10 -N01A	1.5	30, 2x8pair s	7.2	72	135/128
MCP7Y10 -N002	2.0	26, 2x8pair s	8.9	89	156/147
MCP7Y10 -N02A	2.5	26, 2x8pair s	8.9	89	156/147
MCP7Y10 -N003	3.0	26, 2x8pair s	8.9	89	156/147

The minimum assembly bending radius (close to the connector) is 10x the cable's outer diameter. The repeated bend (far from the connector) is also 10x the cable's outer diameter. The single bend (far from the connector) is 5x the cable's outer diameter.

'Combined' end is the 'head' where the cables join together, inserted into the switch. 'Single' end is the 'tail' which plugs into the HCA/NIC in a server.

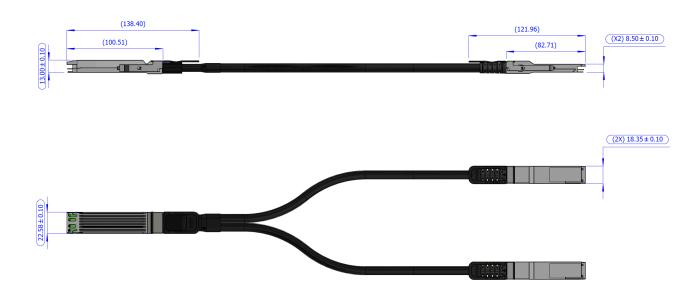
**L = Assembly Space. Minimum value depends on the backshell (connector housing) dimensions = the space for the cable assembly behind the rack door.

Assembly Bending Radius



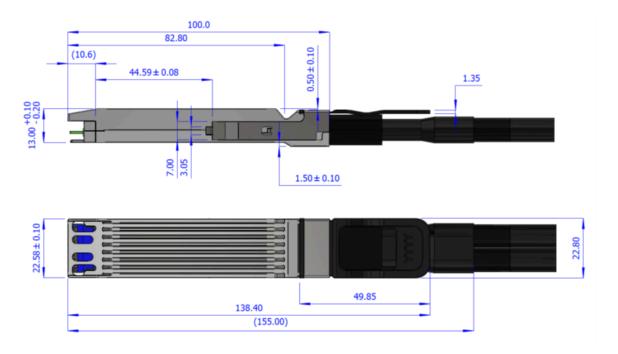
Mechanical Drawings

Cable Dimentions

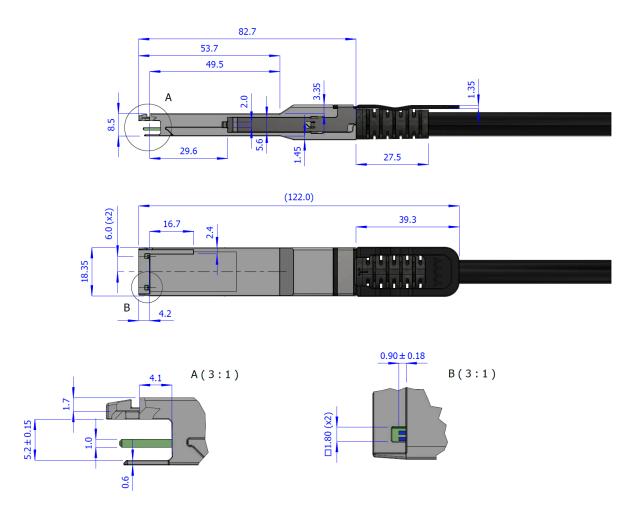


Head/End	Tab Color
OSFP (Head)	Black
QSFP112 (End 1)	Blue
QSFP112 (End 2)	Red

Finned Head Dimensions



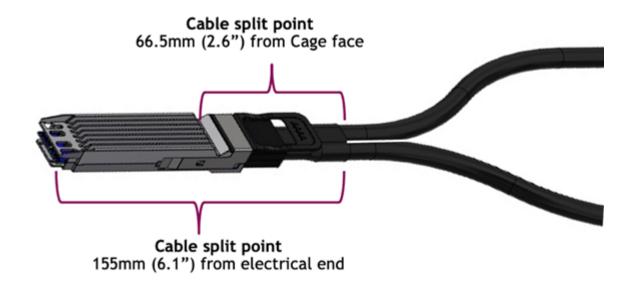
QSFP112 Flat Ends Dimensions



Cable Length Definition (specified in Ordering Information section)



Cable Splitting Point





Note

Images are for illustration purposes only. Product labels, colors, and form may vary.

Labels

Back shell Label

The label applied on back-shell is illustrated below. Note that the Images are for illustration purposes only. Labels look and placement may vary.

OSFP Head Label (Illustration)

Model No: MCP7Y10

PN: MCP7Y10-N001

SN: MTYYWWXXSSSSS

Rev: A2 1m 30AWG

YYYY-MM-DD 800Gb/s

Made In COO



NVIDIA

QSFP112 Ends Label (Illustration)

Model No: MCP7Y10

PN: MCP7Y10-N001

SN: MTYYWWXXSSSSS

Rev: A2 1m 30AWG

YYYY-MM-DD 400Gb/s

Made In COO



NVIDIA



Note

Images are for illustration purposes only. Product labels, colors, and form may vary.

Back-Shell Label Serial Number Legend

Symbol	Description	Notes		
PN – Part Number				
XX	Length	Meter		

Symbol	Description	Notes		
уу	Cable gauge	American wire gauge		
SN – Serial Number				
MN	Manufacturer name	2 characters MT (NVIDIA)		
YY	Year of manufacturing	2 digits		
WW	Week of manufacturing	2 digit		
MS	Manufacturer site	2 characters		
XXXXX	Serial number	5 digits for serial number. Reset at start of week to 00001.		
Miscellaneous				
ZZ	HW and SW revision	2 alpha-numeric characters		
Xm	Cable length	Meter		
XXAWG	Cable gauge	American wire gauge		
YYYY-MM- DD	Year-month-day	Year 4 digits, month 2 digits, day 2 digits		
COO	Country of origin	E.g. China		
QR code	Quick response code	Serial number		

Cable Jacket Label (Middle of Cable)

The following label is applied on the cable's jacket at each end:



(sample illustration)

Note: The serial number and barcode are for NVIDIA internal use only.

Regulatory Compliance

• Safety: CB, TUV, CE, EAC, UKCA

• EMC: CE, FCC, ICES, RCM, VCCI

Ask your NVIDIA FAE for a zip file of the certifications for this product.

FCC Class A Notice

This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense.



Cabling Information

Handling Precautions and Electrostatic Discharge (ESD)

The cable is compatible with ESD levels in typical data center operating environments and certified in accordance with the standards listed in the Regulatory Compliance Section. The product is shipped with protective caps on its connectors to protect it until the time of installation. In normal handling and operation of high-speed cables and optical transceivers, ESD is of concern during insertion into the QSFP cage of the server/switch. Hence, standard ESD handling precautions must be observed. These include use of grounded wrist/shoe straps and ESD floor wherever a cable/transceiver is

extracted/inserted. Electrostatic discharges to the exterior of the host equipment chassis after installation are subject to system level ESD requirements.

Cable Management Guidelines

It is important to follow the instructions and information detailed <u>NVIDIA Cable Management Guidelines and FAQ Application Note</u> to insure proper and optimal installation of this cable and avoid physical damage.

Part Numbers and Description

Ordering PN	Description	
MCP7Y10- N001	NVIDIA passive copper splitter cable, IB twin port NDR 800Gb/s to 2x400Gb/s, OSFP to 2xQSFP112,1m	
MCP7Y10- N01A	NVIDIA passive copper splitter cable, IB twin port NDR 800Gb/s to 2x400Gb/s, OSFP to 2xQSFP112,1.5m	
MCP7Y10- N002	NVIDIA passive copper splitter cable, IB twin port NDR 800Gb/s to 2x400Gb/s, OSFP to 2xQSFP112,2m	
MCP7Y10- N02A	NVIDIA passive copper splitter cable, IB twin port NDR 800Gb/s to 2x400Gb/s, OSFP to 2xQSFP112,2.5m	
MCP7Y10- N003	NVIDIA passive copper splitter cable, IB twin port NDR 800Gb/s to 2x400Gb/s, OSFP to 2xQSFP112,3m	

Document Revision History

Rev	Date	Description
1.3	May 2024	Updated Introduction and Specifications sections.
1.2	Jun. 2023	Added Cable Length Definition to the Mechanical Specifications section.
1.1	Apr. 2023	Formatted and published in HTML. Minor text edits.
1.0	Dec. 2022	Initial release.

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